

L Number	Hits	Search Text	DB	Time stamp
1	2102	((tab near3 lead) and semiconductor and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/19 08:33
2	1640	((tab near3 lead) and semiconductor and (chip die wafer)) and (lead with (electrode bump ball terminal pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/19 08:36
3	123	((((tab near3 lead) and semiconductor and (chip die wafer)) and (lead with (electrode bump ball terminal pad))) and (conductive near1 (vias (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/19 08:37
4	94	(((((tab near3 lead) and semiconductor and (chip die wafer)) and (lead with (electrode bump ball terminal pad))) and (conductive near1 (vias (through adj hole)))) and (seal sealed sealing encapsulant encapsulated encapsulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/19 08:38
5	43	(((((tab near3 lead) and semiconductor and (chip die wafer)) and (lead with (electrode bump ball terminal pad))) and (conductive near1 (vias (through adj hole)))) and (seal sealed sealing encapsulant encapsulated encapsulating)) and (stacked stacking)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/19 08:38